

# **MB05F THRU MB10F**

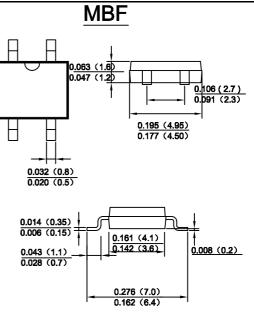
SINGLE PHASE 0.8AMP SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

#### Features

- Glass passivated die construction
- Low forward voltage drop
- High current capability
- High surge current capability
- · Designed for surface mount application
- Plastic material-UL flammability 94V-0

#### **Mechanical Data**

- Case: MB-F, molded plastic
- Terminals: plated leads solderable per MIL-STD-202, Method 208
- · Polarity: as marked on case
- Mounting position: Any
- Marking: type number
- Lead Free: For RoHS / Lead Free Version,



Dimiensions in inches and (milimenters)

### **Maximum Ratings and Electrical Characteristics**

Rating at  $25^{\circ}$ C ambient temperature unless otherwise specified. Single Phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

TYPE NUMBER	SYMBOL	MB05F	MB1F	MB2F	MB4F	MB6F	MB8F	MB10F	UNITS
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	Vrrm								
	Vrwm	50	100	200	400	600	800	1000	V
	VDC								
RMS Reverse Voltage	Vrms	35	70	140	280	420	560	700	V
Average Rectified Output Current (Note 1)@T <sub>A</sub> =40℃ (Note 2)@T <sub>A</sub> =40℃	lo	0.5 0.8							A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	Ifsm	30							A
Forward Voltage per element @IF=0.8A	VFM	1.1							V
Peak Reverse Current @T₄=25 ℃ At Rated DC Blocking Voltage @T₄=125 ℃	lr	5.0 500							uA
Typical Junction Capacitance per leg (Note3)	CJ	13							pF
Typical Thermal Resistance per leg	Reja	60							°C/W
	Rejl	16							
Operating and Storage Temperature Range	TJ,TSTG	-55to+150							°C

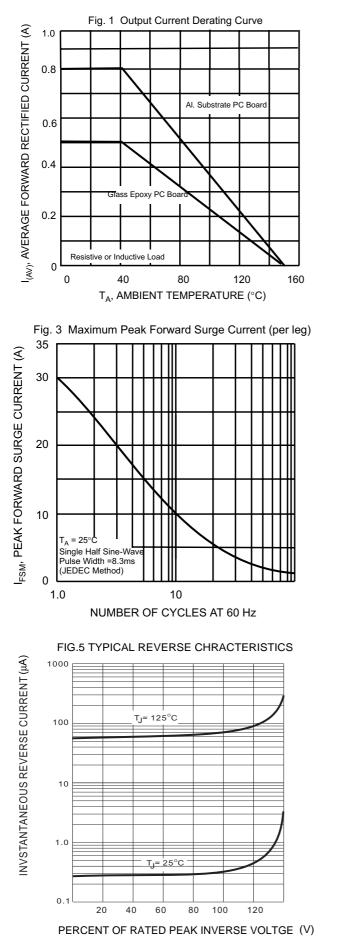
Note:1. Mounted on glass epoxy PC board with 1.3mm<sup>2</sup> solder pad.

- 2. Mounted on aluminum substrate PC board with 1.3mm<sup>2</sup> solder pad.
- 3. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.



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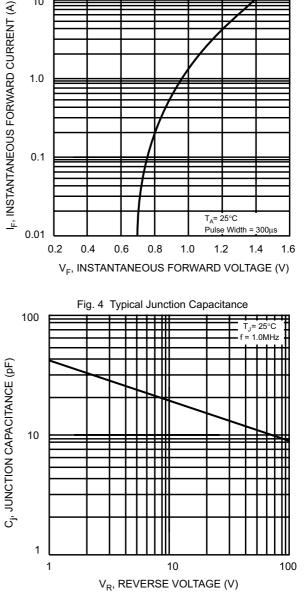


Fig. 2 Typical Forward Characteristics (per leg)